

**Bid Number: GEM/2023/B/3469332**  
**CORRIGENDUM- I**

We refer to our GeM Bid Number: GEM/2023/B/3469332 dated 22.05.2023 for “SELECTION OF VENDOR FOR SUPPLY AND INSTALLATION OF VC APPLICATION SERVERS AND MCU HARDWARE” and pre-bid meeting held on 29.05.2023. In this regard, we issue clarification on certain queries raised by Vendors which is given as under:

SI No.	Point / Section	Page No.	Tender clause	Bidder's Query	Bank's Response
1	GeM Bid Document	6	Bidders can also submit the EMD with Payment online through RTGS / internet banking in Beneficiary name	We request you to kindly confirm if the EMD payment can be done in form of Bank Guarantee.	The provision is already available on GeM
2	Payment Terms /Buyer added GTC (HW_GTC)	17	95% of the total cost of the device/product on delivery & installation plus 100% of GST (wherever applicable) at actuals.  Balance amount of 5% of total cost of device/product will be released on completion of warranty period plus 3 months or against Bank Guarantee for early release of retention money	We request you to please consider the below mentioned payment terms:  1) 30% advance with PO, against BG of equivalent amount 2) 50% against delivery 3) 15% on installation 4) 5% against Retention BG	Bid/tender terms remains unchanged.
3	Annexure IV – Letter of Undertaking from OEM/ Buyer added GTC (HW_GTC)	14	"We..... (Name of the OEM) hereby convey our unconditional acceptance of terms & conditions related to support for our products during Warranty period if M/s (name of bidder) ..... fails to do so....."	We request you to please modify the clause as mentioned below:  We..... (Name of the OEM) shall extend all warranty and support as per the support contract that the bidder has purchased from us (Name of the OEM), and as per our (Name of the OEM) EOL policy. All HW components shall have 5 years of	Bid/tender terms remains unchanged.

			.....through alternate arrangements without any additional cost to the Bank. "	support from the EOL date, subject to our (Name of the OEM) EOL policy. If our authorised bidder fails to meet its obligations w.r.t. our (Name of the OEM) warranty and support, we (Name of the OEM) shall identify an alternate reseller and continue to extend support as per the existing support contract.	
4	Installation /Buyer added GTC (HW_GTC)	12	Installation of all the hardware/ equipment / licenses including unpacking of cartons / boxes, mounting of the hardware/ equipment's and installation will be the responsibility of Bidder. Bidder will have to install the hardware/ equipment's and hand it over to Bank for acceptance testing within a maximum of 1 week from the date of receipt of the deliverables at our office and Bank's notification for installation of the Hardware.	Requesting you to change clause to " Bidder will have to install the hardware/ equipment's and hand it over to Bank for acceptance testing within a maximum of 2 week from the date of receipt of the deliverables at our office and Bank's notification for installation of the Hardware"	Bid/tender terms remains unchanged.
5	Technical Specification - Application Server	Page 1 on technical Specs document and Page 7 of HW_GTC	Rack Server shall have a minimum of one (1) Intel latest generation ice lake Processors with minimum 2.60 GHz & 28 cores, 24 Nos 600 GB 10K HDD drives supporting RAID 0, 1, 5, 6, 10, 50, and 60, 192 GB of DDR4 RAM expandable to 3TB of DDR4 3200 MHz memory supporting advanced memory redundant technologies like Advanced error-correcting code (ECC) and memory mirroring.	Bank has considered only Intel, whereas in X 86 AMD is also an option and it is being used at many BFSI for their various applications.  AMD EPYC is a server processor with higher benchmark in comparison with competition. We request bank to kindly consider AMD EPYC processor with minimum 2.6 GHz and 28 core along with mentioned intel processor.	Rack Server shall have a minimum of one (1) Intel latest generation ice lake Processors <b>or AMD EPYC processors with</b> minimum 2.60 GHz & 28 cores, 24 Nos 600 GB 10K HDD drives supporting RAID 0, 1, 5, 6, 10, 50, and 60, 192 GB of DDR4 RAM expandable to 3TB of DDR4 3200 MHz

					memory supporting advanced memory redundant technologies like Advanced error-correcting code (ECC) and memory mirroring.
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1. Bidders are advised to consider and confirm the above points while submitting the bids.
2. The above shall be complementary in contents with the existing terms and conditions of the Tender/Bid unless otherwise explicitly superseded. All other terms and conditions of the Tender/Bid shall remain unchanged.
3. This Corrigendum – I shall form part of the Bid/Tender dated 22.05.2023.
4. The bidders have to submit “Unconditional Bid”. Conditional bids are liable to be rejected.

**General Manager & Head  
(FM, COA, RDP & PD)**

**Date: 31.05.2023  
Place: Mumbai**

**BANK OF BARODA  
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